PATENT Atty. Dkt. No. APPM/003421.C2/PPC/ECP/CKIM

## IN THE SPECIFICATION:

Please replace paragraph [0001] with the following amended paragraph:

[0001] This application is a continuation of co-pending U.S. Patent Application Serial No. 09/609,347, filed July 5, 2000, which claims benefit of is a continuation of United States Patent Application Serial. No. 09/263,126, filed March 5, 1999, now United States Patent No. 6,136,163. Each of the aforementioned related patent applications is herein incorporated by reference.

Please replace paragraph [0057] with the following amended paragraph:

[0057] Low resistivity, and conversely high conductivity, are directly related to good plating. To ensure low resistivity, the conducting members 765 are preferably made of copper (Cu), platinum (Pt), tantalum (Ta), titanium (Ti), gold (Au), silver (Ag), stainless steel or other conducting materials. Low resistivity and low contact resistance may also be achieved by coating the conducting members 765 with a conducting material. Thus, the conducting members 765 may, for example, be made of copper (resistivity for copper is approximately 2 x  $10^{-8} \Omega \cdot m$ ) and be coated with platinum (resistivity for platinum is approximately 10.6 x  $10^{-8} \,\Omega \cdot m$ ). Coatings such as tantalum nitride (TaN), titanium nitride (TiN), rhodium (Rh), Au, Cu, or Ag on [[a]] conductive base materials such as stainless steel, molybdenum (Mo), Cu, and Ti are also possible. Further, since the contact pads 772, 780 are typically separate units bonded to the conducting connectors 776, the contact pads 772, 780 may comprise one material, such as Cu, and the conducting members 765 another, such as stainless steel. Either or both of the pads 772, 180 and conducting connectors 776 may be coated with a conducting material. Additionally, because plating repeatability may be adversely affected by oxidation which acts as an insulator, the inner contact pads 772 preferably comprise a material resistant to oxidation such as Pt, Ag, or Au.